

Title (en)

Apparatus for electronic assembly with improved interconnect and associated methods

Title (de)

Vorrichtung für eine elektronische Baugruppe mit verbesserter Verbindung und zugehörige Verfahren

Title (fr)

Appareil pour ensemble électronique avec interconnexion améliorée et procédés associés

Publication

EP 2779226 A1 20140917 (EN)

Application

EP 14158359 A 20140307

Priority

US 201313802687 A 20130313

Abstract (en)

An apparatus includes a substrate that includes electronic circuitry. The apparatus further includes a first die that includes electronic circuitry, and at least one shielded interconnect. The shielded interconnect(s) couple(s) electronic circuitry in the substrate to electronic circuitry in the first die.

IPC 8 full level

H01L 23/13 (2006.01); **H01L 23/498** (2006.01); **H01L 23/552** (2006.01)

CPC (source: EP US)

H01L 23/13 (2013.01 - EP US); **H01L 23/3135** (2013.01 - EP US); **H01L 23/49827** (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 24/73** (2013.01 - EP US); **H01L 23/3128** (2013.01 - EP US); **H01L 24/16** (2013.01 - EP US); **H01L 24/45** (2013.01 - EP US); **H01L 25/0652** (2013.01 - EP US); **H01L 2224/131** (2013.01 - EP US); **H01L 2224/16225** (2013.01 - EP US); **H01L 2224/45012** (2013.01 - EP US); **H01L 2224/45015** (2013.01 - EP US); **H01L 2224/45016** (2013.01 - EP US); **H01L 2224/451** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US); **H01L 2224/45147** (2013.01 - EP US); **H01L 2224/45572** (2013.01 - EP US); **H01L 2224/45624** (2013.01 - EP US); **H01L 2224/45647** (2013.01 - EP US); **H01L 2224/45686** (2013.01 - EP US); **H01L 2224/48137** (2013.01 - EP US); **H01L 2224/48145** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/4903** (2013.01 - EP US); **H01L 2224/73257** (2013.01 - EP US); **H01L 2224/8592** (2013.01 - EP US); **H01L 2225/0651** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06537** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/15159** (2013.01 - EP US); **H01L 2924/15311** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19107** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2779226 A1 20140917; CN 104051426 A 20140917; US 2014264783 A1 20140918

DOCDB simple family (application)

EP 14158359 A 20140307; CN 201410090926 A 20140312; US 201313802687 A 20130313